

TIS75

N-Channel General Purpose Amplifier

- This device is designed for low level analog switching, sample and hold circuits and chopper stabilized amplifiers.
- Sourced from process 54.



1. Gate 2. Source 3. Drain

Absolute Maximum Ratings * Ta=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V_{DG}	Drain-Gate Voltage	30	V
V_{GS}	Gate-Source Voltage	-30	V
I _{GF}	Forward Gate Current	10	mA
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 ~ +150	°C

^{*} These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150 degrees C.
 These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Electrical Characteristics T_a=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charac	cteristics					
V _{(BR)GSS}	Gate-Source Breakdown Voltage	$I_G = 1.0 \mu A, V_{DS} = 0$	-30			V
I _{GSS}	Gate Reverse Current	V _{GS} = 15V, V _{DS} = 0 V _{GS} = 15V, V _{DS} = 0, T _a = 100°C			-2.0 -5.0	nA μA
I _D (off)	Drain Cutoff Leakage Current	$V_{GS} = 15V$, $V_{DS} = 0$, $V_{A} = 100 \text{ G}$ $V_{DS} = 15V$, $V_{GS} = -10V$, $V_{DS} = 15V$, $V_{GS} = -10V$, $V_{GS} = 100 \text{ G}$			-2.0 -5.0	nA μA
V _{GS} (off)	Gate-Source Cutoff Voltage	V _{DS} = 20V, I _D = 4.0nA	-0.8		-4.0	V
On Charac	teristics *	•	<u>'</u>			
I _{DSS}	Zero-Gate Voltage Drain Current *	V _{DS} = 15V, V _{GS} = 0	8		80	mA
r _{DS} (on)	Drain-Source On Resistance	$V_{DS} \le 0.1V, V_{GS} = 0$			60	Ω
Small Sign	nal Characteristics	•	<u>'</u>		•	•
C _{iss}	Input Capacitance	V _{DS} = 0, V _{GS} = -10V, f = 1.0MHz			18	pF
C _{rss}	Reverse Transfer Capacitance	V _{DS} = 0, V _{GS} = -10V, f = 1.0MHz			8.0	pF
Switching	Characteristics	•	<u>'</u>			
t _r	Rise Time	$V_{GS}(off) = -4.0V, V_{GS}(on) = 0,$			10	ns
t _{on}	Turn-On Time	I _D = 5.0mA, V _{DS} = 10V			10	ns
t _{off}	Turn-Off Time				100	ns

^{*} Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 3.0%

Thermal Characteristics T _a =25°C unless otherwise noted								
Symbol	Parameter	Max.	Units					
P _D	Total Device Dissipation Derate above 25°C	350 2.8	mW mW/ [°] C					
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125	°C/W					
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W					

Package Dimensions

TO-92





